


# MATERIAL DATA SHEET



Material #	<b>CZRQR series(0402) (Halogen Free)</b>	
Product Line	SOD-923F	
Date	2011/10/5	
Rev.	A	

## COMPONENT DETAILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)
1	FR-4 Board	Substrate/ Terminal	0.223	Copper	7440-50-8	43.00%	29.00%
				Nickel	7440-02-0	3.677%	
				Gold	7440-57-5	0.099%	
				Continuous Filament Fiber Glass	65997-17-3	53.22%	
2	Wafer	Diode	0.029	Silicon	7440-21-3	94.64%	3.77%
				Aluminum	7429-90-5	0.23%	
				Titanium	7440-32-6	0.04%	
				Gold	7440-57-5	5.09%	
3	Al wire	Conductor	0.001	Aluminum	7429-90-5	99.00%	0.13%
				Silicon	7440-21-3	1.00%	
4	Silver paste	Welding	0.005	Modified Epoxy Resin	29690-82-2	5~25%	0.65%
				Silver	7440-22-4	76~85%	
				Imidazole	827-43-0	1~4%	
				Amide	461-58-5	1~4%	
5	Molding Compound	Outer	0.511	Silica	60676-86-0	70~90%	66.45%
				Epoxy Resin	129915-35-1	6~16%	
				Phenolic Resin	26834-02-6	5~15%	
				Carbon Black	1333-86-4	0.1~1%	
		Total weight	0.769				